

## AMENDMENT TO CLAIMS

Please cancel without prejudice claims 1-20 and 35-40 as shown below. All pending claims are reproduced below, including those that remain unchanged.

1 - 20. Canceled.

21. (Original) A method for planarizing a surface of a workpiece, comprising:  
translating at least one of a workpiece and a plasma torch;  
depositing material on the surface of the workpiece using the plasma torch;  
removing material from the surface of the workpiece using a discharge from the plasma torch; and  
using reactive atom plasma processing to redeposit the removed material on the surface of the workpiece.
22. (Original) A method according to claim 21, further comprising:  
introducing reactive species into the plasma through a central channel in the plasma torch.
23. (Original) A method according to claim 21, further comprising:  
placing a precursor in a central channel of the plasma.
24. (Original) A method according to claim 21, further comprising:  
controlling the mass flow of a precursor into the processing chamber.
25. (Original) A method according to claim 21, further comprising:  
selecting a concentration of precursor to be introduced into a central channel of the plasma.
26. (Original) A method according to claim 21, further comprising:  
introducing a plasma gas through an outer tube of the plasma torch.

27. (Original) A method according to claim 21, further comprising:  
coupling energy to the discharge in an annular region of the plasma torch.
28. (Original) A method according to claim 21, further comprising:  
introducing an auxiliary gas through a second of three concentric tubes in the plasma torch.
29. (Original) A method according to claim 21, further comprising:  
maintaining the temperature of the plasma.
30. (Original) A method according to claim 21, wherein:  
the depositing and removing steps occur at atmospheric pressure.
31. (Original) A method according to claim 21, further comprising:  
altering the chemistry of the surface of the workpiece with the plasma.
32. (Original) A method according to claim 21, further comprising:  
controlling the removal rate at which material is removed from the surface of the workpiece.
33. (Original) A method according to claim 21, further comprising:  
controlling the deposition rate at which material is deposited onto the surface of the workpiece.
34. (Original) A method according to claim 21, further comprising:  
controlling the redeposition rate at which material removed from the surface during processing is redeposited on the surface.

35-40. Canceled.